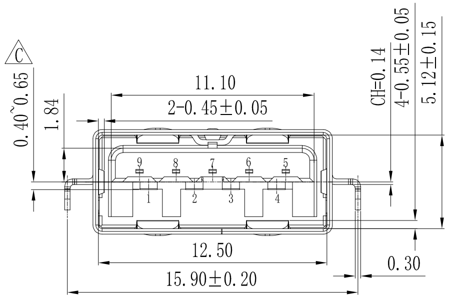

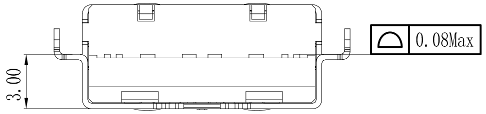

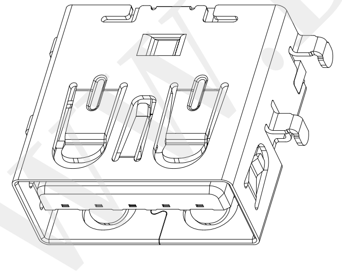

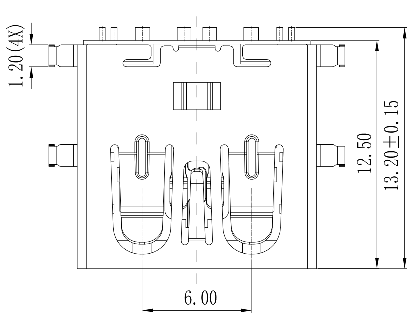

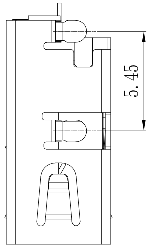

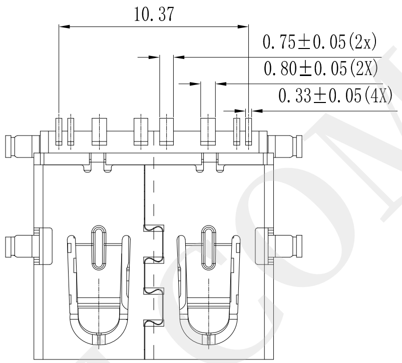

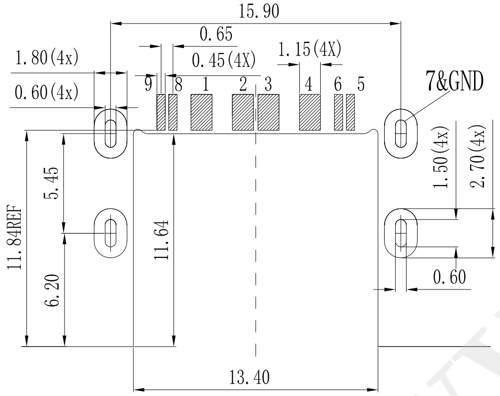

TOLERANCE: ±0.05, RECOMMENDED PCB LAYOUT

(TOP VIEW)

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

NOTE:

1.MATERIAL:
  1.1 INSULATOR:LCP+30%GF, UL94 V-0.
  1.2 CONTACT 1~4PIN: C5191-EH.
  1.3 CONTACT 5~9PIN: C5191-EH.
  1.4 SHELL: SUS304 3/4H

2. PLATING:
  2.1 CONTACT:
    CONTACT AREA: GOLD PLATING.
    SOLDER AREA: 100u″ Min MATTE TIN PLATING.
    UNDER PLATE: 50u″ Min NICKEL PLATING.
  2.2 SHELL:50u″ Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:
  3.1 ELECTRICAL CHARACTERISTICS;
    CONTACTRESISTANCE:30mΩ MAXIMUM
    CONTACT CURRENT RATING: 3A
    DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.
    INSULATION RESISTANCE: 100 MEGOHMS MIN
    OPERATING TEMPEROTURE: -25° C ～ +85° C
  3.2 MECHANICAL:
    MATING FORCE: 8-25N .
    UNMATING FORCE: 10-25N .
    After lifespan testing: 6N Min.

4.PART MUST COMPLY ROHS SPECIFICATION

5.WAVE SOLDER:THE CONNECTOR SHALL BE MOUNENTD ON THE PCB.THE TEMPERATURE OF THE SOLDER SHALL BE 260±5 ° C AND IMMERSION DURATION 5 SECONDS.

6.ROHS.HF

HOAUC 华宇创

深圳市华宇创精密电子有限公司

TOLERANCE: **X.X ±0.30** **X.XX ±0.25** **X.XXX ±0.15** **X.° ±2° X.X° ±0.5°**	**DRAWED BY :** 陈一鸣	**DATE :** 2014-02-23	**PART NAME:** USB 3.1 AF 10Gbps 沉板 H=3.0mm	
UNIT: mm [inch]	**CHECKED BY:** 马跃	**DATE :** 2014-02-23	**PART NO.**	HYC185-USBA09-300
			MOLD NO.	
SCALE:1:1 **SIZE: A4**	**APPROVED BY:** 邱敏	**DATE :** 2014-02-23	**DRAW NO:**	HYC-2604281556
			SHEET NO.	1 OF 1

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